

ABSTRACT

5 A method of depositing a copper interconnection layer
on a substrate for use in a flat panel display
interconnection system, comprising the steps of:

- a) Coating said substrate with a photoresist layer;
- b) Patterning said photoresist layer to obtain a
10 patterned photoresist substrate comprising at least one
trench patterned into said photoresist layer;
- c) Providing a first catalysation layer onto the
patterned photoresist substrate;
- d) Providing an electroless plated layer of an
insulation layer deposited onto said first catalysation
15 layer;
- e) Removing the successively superimposed photoresist
layer, catalysation layer and insulation layer except in
the at least one trench, to obtain a pattern of the first
catalysation layer with an insulation layer deposited
20 thereon.

Figure 1